Materials Declaration

Package	TSSOP
Body Size	4.4
LeadCount	14
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Byphenyl resin	9	8.78 E-04	15270
SiO2 Filler	85	8.30 E-03	144218
Phenol Resin	5	4.88 E-04	8483
Antimony_Sb2O3	0.5	4.88 E-05	848
Brominated Resin	0.5	4.88 E-05	848

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	3.08 E-02	535728
Ni	3	9.61 E-04	16707
Si	0.65	2.08 E-04	3620
Mg	0.15	4.81 E-05	835

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	5.00 E-04	8691

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	1.24 E-03	21554

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	2.74 E-04	4763

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	1.36 E-02	236032

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	4.68 E-05	813
Ag Filler	75	1.40 E-04	2438

Package Totals

Weight (g)	PPM
5.75 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	ICP AES
Cd	Not Detected	ICP AES
Hg	Not Detected	ICP AES
Cr+6	Not Detected	DIN 53314

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability t
any inaccuracy of such information.

ADI Proprietary

Materials Declaration

Package	TSSOP
Body Size	4.4
LeadCount	14
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Byphenyl resin	9	8.78 E-04	15270
SiO2 Filler	85	8.30 E-03	144218
Phenol Resin	5	4.88 E-04	8483
Antimony_Sb2O3	0.5	4.88 E-05	848
Brominated Resin	0.5	4.88 E-05	848

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	3.08 E-02	535728
Ni	3	9.61 E-04	16707
Si	0.65	2.08 E-04	3620
Mg	0.15	4.81 E-05	835

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	5.00 E-04	8691

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.05 E-03	18321
Pb	15	1.86 E-04	3.23 E+03

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	2.74 E-04	4763

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	1.36 E-02	236032

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	4.68 E-05	813
Ag Filler	75	1.40 E-04	2438

Package Totals

Weight (g)	PPM
5.75 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	ICP AES
Cd	Not Detected	ICP AES
Hg	Not Detected	ICP AES
Cr+6	Not Detected	DIN 53314

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

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